



P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} Max	I _D T _A = +25°C
-60V	$105m\Omega$ @ $V_{GS} = -10V$	-3.3A
-00 v	130mΩ @ $V_{GS} = -4.5V$	-3.0A

Features

- Low On-Resistance
- Low Input Capacitance
- · Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description

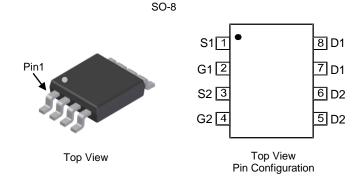
This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}), yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

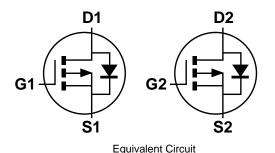
Applications

- DC-DC Converters
- Power Management Functions
- Backlighting

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.074 grams (Approximate)





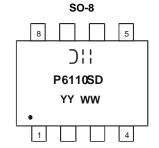
Ordering Information (Note 4)

Part Number	Case	Packaging
DMP6110SSD-13	SO-8	2,500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



⊃¦¦ = Manufacturer's Marking P6110SD = Product Type Marking Code YYWW = Date Code Marking YY or YY = Year (ex: 16 = 2016) WW = Week (01 - 53)



Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V _{DSS}	-60	V	
Gate-Source Voltage		V _{GSS}	±20	V
Continuous Drain Current (Note 6) V 40V	$T_C = +25$ °C $T_C = +70$ °C	I _D	-7.8 -6.3	А
Continuous Drain Current (Note 6) V _{GS} = -10V	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	-3.3 -2.7	А
Pulsed Drain Current (380µs Pulse, 1% Duty Cycle)	I _{DM}	-24	Α	
Maximum Continuous Body Diode Forward Current (Note 6)		I _S	-1.8	Α
Avalanche Current (Note 9) L = 0.1mH		I _{AS}	-19	А
Avalanche Energy (Note 9) L = 0.1mH		E _{AS}	18	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Total Dawar Dissipation (Note 5 % 7)	T _A = +25°C		1.2	W
Total Power Dissipation (Note 5 & 7)	T _A = +70°C	P_D	0.9	
Total Power Dissipation (Note 5 & 8)	T _A = +25°C		1.2	
Thermal Resistance, Junction to Ambient (Note 5 & 7)	Steady State		104	°C/W
Thermal Resistance, Junction to Ambient (Note 5 & 7)	t<10s	$R_{\Theta JA}$	45	
Thermal Resistance, Junction to Ambient (Note 5 & 8)	Steady State		100	
Total Power Dissipation (Note 6 & 7)	T _A = +25°C		1.7	W
Total Power Dissipation (Note 6 & 7)	T _A = +70°C	P_{D}	1.1	
Total Power Dissipation (Note 6 & 8)	T _A = +25°C		1.8	
Thormal Basistanes, Junction to Ambient (Note 6 9 7)	Steady State		74	°C/W
Thermal Resistance, Junction to Ambient (Note 6 & 7)	t<10s	$R_{\Theta JA}$	37	
Thermal Resistance, Junction to Ambient (Note 6 & 8)	Steady State		71	
Thermal Resistance, Junction to Case (Note 6 & 7)		R _{OJC}	15	
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 7. For a dual device with one active die.
- 8. For a device with two active die running at equal power.
 9. Ias and Eas rating are based on low frequency and duty cycles to keep T_J = +25°C.



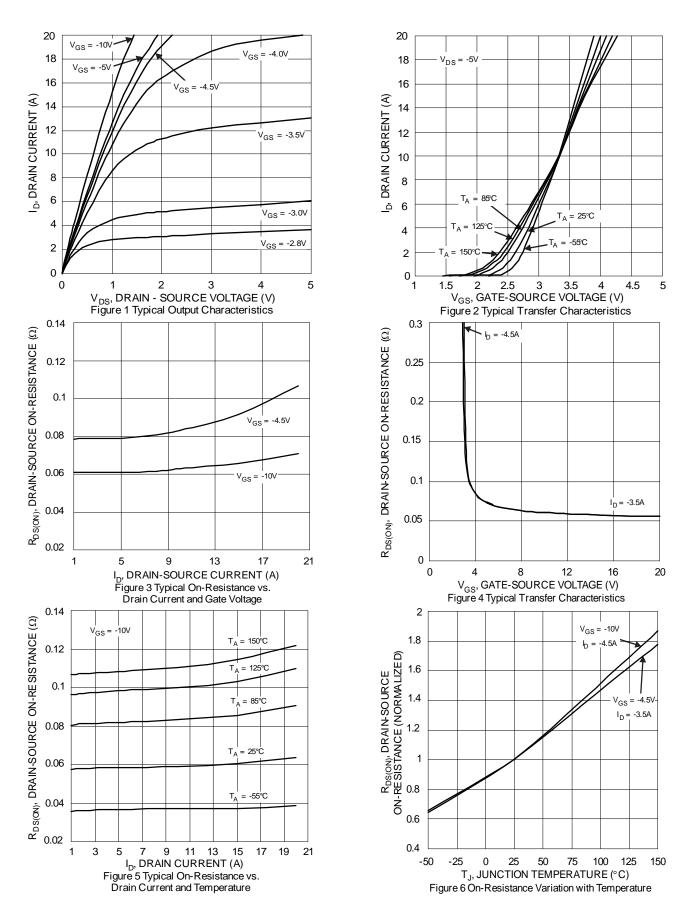
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 10)							
Drain-Source Breakdown Voltage	BV _{DSS}	-60		_	V	$V_{GS} = 0V, I_{D} = -250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	-1	μΑ	V _{DS} = -48V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	100	nA	$V_{GS} = \pm 16V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 10)							
Gate Threshold Voltage	V _{GS(TH)}	-1		-3	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain-Source On-Resistance				105	mΩ	$V_{GS} = -10V, I_D = -4.5A$	
Static Dialii-Source On-Resistance	R _{DS(ON)}	_	_	130	11177	V _{GS} = -4.5V, I _D =-3.5A	
Diode Forward Voltage	V_{SD}	_	-0.7	-1.2	V	$V_{GS} = 0V, I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 11)							
Input Capacitance	C _{ISS}	_	969	_	pF		
Output Capacitance	Coss		57		pF	VDS = -30V, VGS = 0V, f = 1.0MHz	
Reverse Transfer Capacitance	C _{RSS}	_	44	_	pF]	
Gate Resistance	R _G	_	13.7	_	Ω	VDS = 0V, VGS = 0V, f = 1.0MHz	
Total Gate Charge (V _{GS} = -4.5V)	Q _G	_	8.2	_	nC	VDS = -30V, ID = -12A	
Total Gate Charge (V _{GS} = -10V)	Q_{G}		17.2	_	nC		
Gate-Source Charge	Q _{GS}	_	3.0	_	nC	VDS = -30V, ID = -12A	
Gate-Drain Charge	Q_{GD}	_	3.1	_	nC]	
Turn-On Delay Time	t _{D(ON)}	_	4.4	_	ns		
Turn-On Rise Time	t _R	_	23	_	ns	$V_{GS} = -10V, V_{DS} = -30V, R_{GEN} =$	
Turn-Off Delay Time	t _{D(OFF)}	_	34	_	ns	3Ω, ID=-12A	
Turn-Off Fall Time	t _F	_	42	_	ns		
Body Diode Reverse Recovery Time	t _{RR}	_	13.2	_	ns	1 404 11/11 4004/	
Body Diode Reverse Recovery Charge	Q_{RR}		6.18	_	nC	$I_S = -12A$, di/dt = 100A/ μ s	

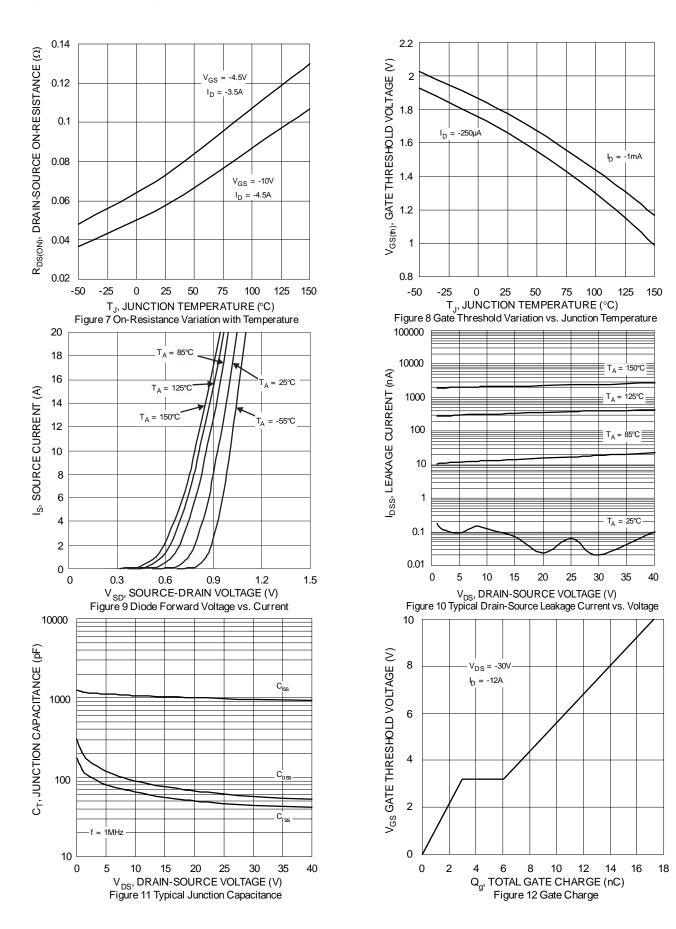
Notes:

Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.

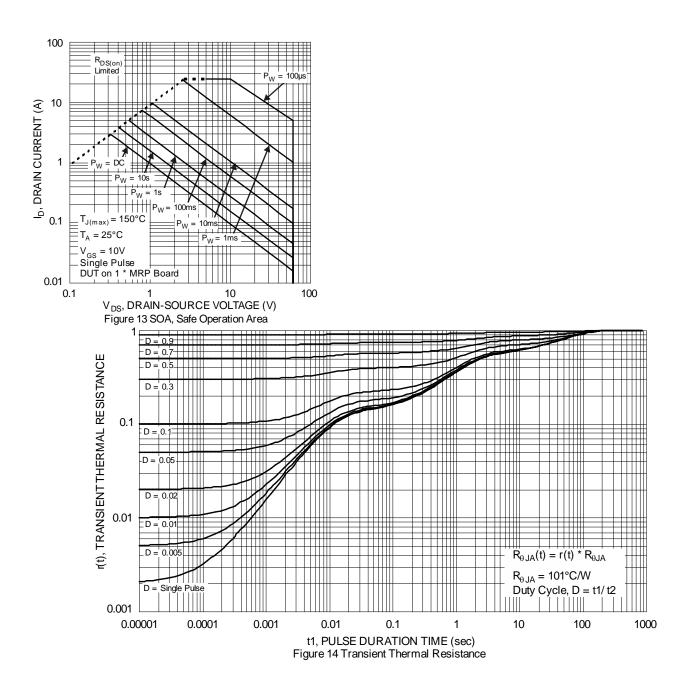










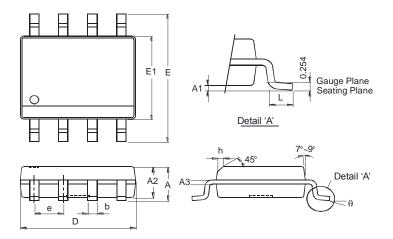




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

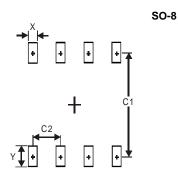
SO-8



SO-8				
Dim	Min	Max		
Α	1	1.75		
A1	0.10	0.20		
A2	1.30	1.50		
A3	0.15	0.25		
b	0.3	0.5		
D	4.85	4.95		
Е	5.90	6.10		
E1	3.85	3.95		
е	1.27 Typ			
h	_	0.35		
L	0.62	0.82		
θ	0°	8°		
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
Х	0.60
Y	1.55
C1	5.4
C2	1.27



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